

Listing of Claims:

1. (Currently Amended) A semiconductor package comprising:
a semiconductor substrate including a device region on ~~one~~ a
first surface thereof, and a connecting pad electrically
connected to the device region;

5 a connecting wire which is formed on a side of the first
surface of the semiconductor substrate and which includes a first
end electrically connected to the connecting pad and a second end
extending outside of the semiconductor substrate;

10 an insulating film formed on the second surface of the
semiconductor substrate and the connecting wire and having a hole
at a position corresponding to the second end of the connecting
wire;

15 a support substrate formed on ~~a~~ the side of ~~one~~ the first
surface of the semiconductor substrate so as to support the
semiconductor substrate;

an external electrode formed on ~~a side of the other surface~~
~~of the semiconductor substrate~~ the insulating film; and

20 a ~~connecting means, partially extended outside the~~
~~semiconductor substrate,~~ distribution wire for electrically
connecting the connecting ~~pad~~ wire and external electrode via the
hole in the insulating film.

Claims 2 and 3 (Canceled).

4. (Currently Amended) A ~~The~~ package according to claim 3 1, wherein the connecting wire ~~includes~~ comprises a metal plating layer.

5. (Currently Amended) A ~~The~~ package according to claim 3 1, wherein the connecting wire includes a portion in close contact with ~~one~~ the first surface of the semiconductor substrate.

6. (Currently Amended) A ~~The~~ package according to claim 3 1, wherein the connecting wire is formed in close contact with the support substrate.

7. (Currently Amended) A ~~The~~ package according to claim 3 1, ~~which further comprises~~ comprising a projecting connecting electrode between the connecting pad and connecting wire.

Claim 8 (Canceled).

9. (Currently Amended) A semiconductor package ~~according~~
~~to claim 2,~~ comprising:

a semiconductor substrate including a device region on a
first surface thereof, and a connecting pad electrically
5 connected to the device region;

a support substrate formed on a side of the first surface
of the semiconductor substrate;

an external electrode formed on a side of a second surface
of the semiconductor substrate; and

10 connecting means, partially extended outside the
semiconductor substrate, for electrically connecting the
connecting pad and external electrode;

wherein the connecting means includes a distribution wire
extended to the side of the second surface of the semiconductor
15 substrate, and a connecting wire formed on a surface of the
support substrate ~~, which opposes~~ opposing the semiconductor
substrate, ~~and having one~~ wherein the connecting wire comprises
a first end portion connected to the connecting pad, and ~~the~~
~~other~~ a second end portion extended outside the semiconductor
20 substrate, and

wherein a columnar electrode is formed on the ~~other~~ second
end portion of the connecting wire, and the distribution wire is
connected to the columnar electrode.

10. (Currently Amended) A The package according to claim 9, wherein an insulating film is formed between (i) the ~~other~~ second surface of the semiconductor substrate, ~~which includes~~ and the connecting wire ~~extended~~ extending outside the semiconductor substrate and the columnar electrode, and (ii) the distribution wire.

Claim 11 (Canceled).

12. (Currently Amended) A The package according to claim ~~11~~ 1, wherein the external electrode ~~has~~ comprises a columnar electrode, and a solder ball is formed on the columnar external electrode.

13. (Currently Amended) A The package according to claim 1, wherein the device region ~~has~~ comprises a photoelectric conversion device region.

14. (Currently Amended) A The package according to claim 1, wherein the support substrate ~~has~~ comprises a glass substrate.

15. (Currently Amended) ~~A~~ The package according to claim 14, wherein one of a transparent adhesive layer ~~or~~ and a transparent encapsulating layer is formed between the semiconductor substrate and glass substrate.

Claims 16-28 (Canceled).

29. (New) The package according to claim 12, wherein an encapsulating film is formed around the columnar electrode on the insulating film.